



Material Content Data Sheet

Sales Product Name	TLE4226G			Issued		29. August 2013		
MA#	MA000044032							
Package	P-DSO-24-3			Weight*		719.22 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	11.064	1.54	1.54	15384	15384
leadframe	non noble metal	zinc	7440-66-6	0.227	0.03		316	
	inorganic material	phosphorus	7723-14-0	0.057	0.01		79	
	non noble metal	iron	7439-89-6	4.540	0.63		6312	
	non noble metal	copper	7440-50-8	184.335	25.63	26.30	256297	263004
wire	noble metal	gold	7440-57-5	0.483	0.07	0.07	671	671
encapsulation	organic material	carbon black	1333-86-4	5.641	0.78		7843	
	inorganic material	antimonytrioxide	1309-64-4	10.769	1.50		14972	
	plastics	epoxy resin	-	33.331	4.63		46343	
	plastics	brominated resin	-	76.918	10.69		106946	
	inorganic material	silicondioxide	60676-86-0	386.129	53.70	71.30	536873	712977
leadfinish	non noble metal	lead	7439-92-1	0.360	0.05		500	
	non noble metal	tin	7440-31-5	1.294	0.18	0.23	1799	2299
plating	noble metal	silver	7440-22-4	1.026	0.14	0.14	1426	1426
glue	plastics	epoxy resin	-	0.610	0.08		848	
	noble metal	silver	7440-22-4	2.439	0.34	0.42	3391	4239
*deviation	< 10%	Sum in total:			100,00			1000000

Important Remarks:

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